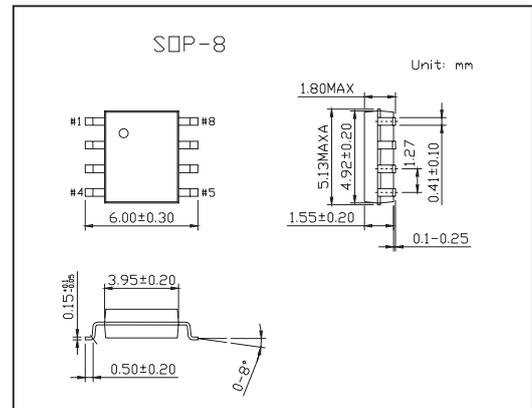
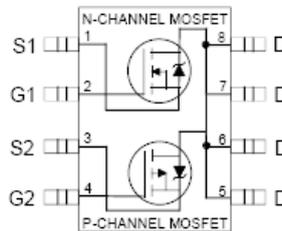


KRF7389

■ Features

- Generation V Technology
- Ultra Low On-Resistance
- Complimentary Half Bridge
- Surface Mount
- Fully Avalanche Rated



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V _{DS}	30	-30	V
Continuous Drain Current Ta = 25°C	I _D	7.3	-5.3	A
Continuous Drain Current Ta = 70°C	I _D	5.9	-4.2	
Pulsed Drain Current *1	I _{DM}	30	-30	
Continuous Source Current (Diode Conduction)	I _S	2.5	-2.5	
Power Dissipation @Ta= 25°C	P _D	2.5		W
@Ta= 70°C		1.6		
Gate-to-Source Voltage	V _{GS}	±20		V
Single Pulse Avalanche Energy	E _{AS}	82	140	mJ
	I _{AR}	4.0	-2.8	A
Repetitive Avalanche Energy	E _{AR}	0.20		mJ
Peak Diode Recovery dv/dt *2	dv/dt	3.8	-2.2	V/ns
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to + 150		°C
Maximum Junction-to-Ambient *3	R _{θJA}	50		°C/W

*1 Repetitive rating; pulse width limited by max. junction temperature.

*2 N-Channel I_{SD} ≤ 4.0A, di/dt ≤ 74A/μs, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C

P-Channel I_{SD} ≤ -2.8A, di/dt ≤ 1500A/μs, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C

*3 Surface mounted on FR-4 board, t ≤ 10sec.

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit		
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250 μ A	N-Ch	30			V	
		V _{GS} = 0V, I _D = 250 μ A	P-Ch	-30				
Breakdown Voltage Temp. Coefficient	ΔV _{(BR)DSS} / ΔT _J	I _D = 1mA, Reference to 25°C	N-Ch		0.022		V/°C	
		I _D = 1mA, Reference to 25°C	P-Ch		0.022			
Static Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 5.8A*1	N-Ch		0.023	0.029	Ω	
		V _{GS} = 4.5V, I _D = 4.7A*1			0.032	0.046		
Static Drain-to-Source On-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -4.9A*1	P-Ch		0.042	0.058		
		V _{GS} = -4.5V, I _D = -3.6A*1			.076	0.098		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μ A	N-Ch	1			V	
		V _{DS} = V _{GS} , I _D = -250 μ A	P-Ch	-1.0				
Forward Transconductance	g _{fs}	V _{DS} = 15V, I _D = 5.8A*1	N-Ch		14		S	
		V _{DS} = -15V, I _D = -4.9A*1	P-Ch		7.7			
Drain-to-Source Leakage Current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V	N-Ch			1.0	μ A	
		V _{DS} = -24V, V _{GS} = 0V	P-Ch			-1.0		
		V _{DS} = 24V, V _{GS} = 0V, T _J = 55°C	N-Ch			25		
		V _{DS} = -24V, V _{GS} = 0V, T _J = 55°C	P-Ch			-25		
Gate-to-Source Forward Leakage	I _{GSS}	V _{GS} = ±20V	N-Ch			±100	nA	
			P-Ch			±100		
Total Gate Charge	Q _g	N-Channel I _D = 5.8A, V _{DS} = 15V, V _{GS} = 10V	N-Ch		22	33	nC	
Gate-to-Source Charge	Q _{gs}		P-Ch		23	34		
		Gate-to-Drain ("Miller") Charge	Q _{gd}	P-Channel I _D = -4.9A, V _{DS} = -15V, V _{GS} = -10V	N-Ch			2.6
P-Ch					3.8	5.7		
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 15V, I _D = 1.A, R _G = 6.0 Ω	N-Ch		8.1	12		ns
			P-Ch		13	19		
Rise Time	t _r	R _D = 15 Ω P-Channel	N-Ch		8.9	13		
			P-Ch		13	20		
Turn-Off Delay Time	t _{d(off)}	V _{DD} = -15V, I _D = -1.8A, R _G = 6.0 Ω R _D = 15 Ω	N-Ch		26	39		
			P-Ch		34	51		
Fall Time	t _f		N-Ch		17	26		
			P-Ch		32	48		
Input Capacitance	C _{iss}	N-Channel V _{GS} = 0V, V _{DS} = 25V, f = 1.0MHz	N-Ch		650		pF	
			P-Ch		710			
Output Capacitance	C _{oss}	P-Channel V _{GS} = 0V, V _{DS} = -25V, f = 1.0MHz	N-Ch		320			
			P-Ch		380			
Reverse Transfer Capacitance	C _{rss}		N-Ch		130			
			P-Ch		180			
Continuous Source Current (Body Diode)	I _S		N-Ch			2.5	A	
			P-Ch					-2.5
Pulsed Source Current (Body Diode) *2	I _{SM}		N-Ch			30		
			P-Ch					-30



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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Diode Forward Voltage	V _{SD}	T _J = 25°C, I _S = 1.7A, V _{GS} = 0V*1	N-Ch	0.78	1.0	V
		T _J = 25°C, I _S = -1.7A, V _{GS} = 0V*1	P-Ch	-0.78	-1.0	
Reverse Recovery Time	t _{rr}	N-Channel T _J = 25°C, I _F = 1.7A, di/dt = 100A/μs*1	N-Ch	45	68	ns
			P-Ch	44	66	
Reverse RecoveryCharge	Q _{rr}	P-Channel T _J = 25°C, I _F = -1.7A, di/dt = -100A/μs*1	N-Ch	58	87	nC
			P-Ch	42	63	

*1 Pulse width ≤ 300 μs; duty cycle ≤ 2%.

*2 Repetitive rating; pulse width limited by max. junction temperature.